

CLAIMS

1. A solder comprising zinc at 7 to 10 weight % both inclusive, bismuth at 0.001 to 6 weight % both inclusive, silver at 0.001 to 0.1 weight % both inclusive,
5 and the remainder of tin.

2. A solder comprising Sn-Zn alloy(s) having a single composition ratio or a plurality of composition ratios, and Sn-Bi-Ag alloy(s) having a single composition ratio or a plurality of composition ratios, said solder including zinc at 7 to 10
10 weight % both inclusive, bismuth at 0.001 to 6 weight % both inclusive, silver at 0.001 to 0.1 weight % both inclusive, and the remainder of tin when said alloys are melted in mixture.

3. The solder as set forth in claim 1 or 2, wherein said solder is in the form
15 of powder.

4. The solder as set forth in claim 3, wherein said powder has a diameter in the range of 20 to 40 micrometers both inclusive.

20 5. The solder as set forth in claim 3 or 4, wherein a difference between a maximum diameter of said powder and a minimum diameter of said powder is equal to or smaller than 10 micrometer.

6. The solder as set forth in any one of claims 3 to 5, wherein said solder is
25 mixed in flux.

7. The solder as set forth in claim 6, wherein said flux has a concentration in the range of 9 to 13 weight % both inclusive.

8. A circuit substrate unit comprising a circuit board, and at least one electronic component soldered onto said circuit board, characterized in that said electronic component is soldered onto said circuit board through a solder defined in any one of claims 1 to 7.

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